

Special Issue

Design, Analysis, Intelligent Control and Optimization of Industrial and Manufacturing Processes

Message from the Guest Editors

We aim to promote discussion among researchers and engineers and share the most recent advancements in this field. We encourage the submission of studies that cover aspects related to the industrial and manufacturing processes, including, but not limited to, the following topics:

- Smart manufacturing, design, analysis, intelligent control, and optimization of the processes;
- Special technologies in manufacturing, like additive manufacturing (3D printing);
- High-precision manufacturing optimized techniques, like surface milling, etching, electroforming and die casting;
- Techniques for improved manufacturing throughput;
- Industry 4.0 and its main technologies, such as the Internet of Things (IoT), cyber-physical systems (CPS), big data, simulation and digital twins, advanced robotics, augmented reality, artificial intelligence, machine learning, etc.;
- Trends in supply chain management and logistics;
- Advanced materials for industry, manufacturing, and products, like high-strength materials, lightweight materials, and carbon fiber;
- New or hybrid forms of manufacturing and manufacturing systems.

Guest Editors

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Deadline for manuscript submissions

closed (20 July 2025)



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About the Journal

Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal *Applied Sciences* has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

Editor-in-Chief

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